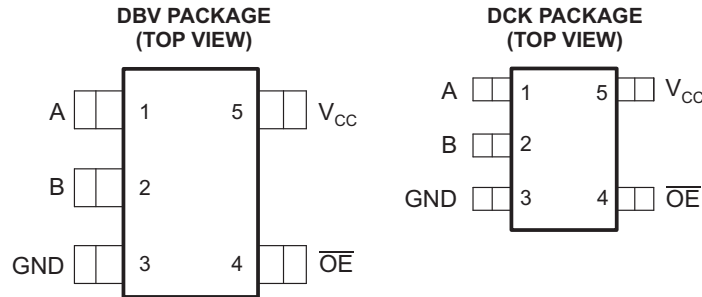


FEATURES

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Control Input Levels
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II



See mechanical drawings for dimensions.

DESCRIPTION/ORDERING INFORMATION

The SN74CBTD1G384 features a single high-speed line switch. The switch is disabled when the output-enable (\overline{OE}) input is high. A diode to V_{CC} is integrated on the chip to allow for level shifting from 5-V signals at the device inputs to 3.3-V signals at the device outputs.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
-40°C to 85°C	SOT (SOT-23) – DBV	Reel of 3000	SN74CBTD1G384DBVR	P8D_
		Reel of 250	SN74CBTD1G384DBVT	
	SOT (SC-70) – DCK	Reel of 3000	SN74CBTD1G384DCKR	P8_
		Reel of 250	SN74CBTD1G384DCKT	

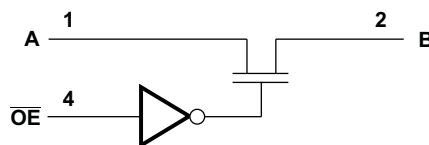
(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

(2) The actual top-side marking has one additional character that designates the assembly/test site.

FUNCTION TABLE

INPUT \overline{OE}	FUNCTION
L	A port = B port
H	Disconnect

LOGIC DIAGRAM (POSITIVE LOGIC)



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SN74CBTD1G384

SINGLE FET BUS SWITCH

WITH LEVEL SHIFTING

SCDS066K–JULY 1998–REVISED JUNE 2006

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
V _{CC}	Supply voltage range	–0.5	7	V	
V _I	Input voltage range ⁽²⁾	–0.5	7	V	
Continuous channel current			128	mA	
I _{IK}	Input clamp current	V _{I/O} < 0		–50	mA
θ _{JA}	Package thermal impedance ⁽³⁾	DBV package		206	°C/W
		DCK package		252	
T _{stg}	Storage temperature range	–65	150	°C	

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾⁽²⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5	5.5	V
V _{IH}	High-level control input voltage	2		V
V _{IL}	Low-level control input voltage		0.8	V
T _A	Operating free-air temperature	–40	85	°C

- (1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
- (2) In applications with fast edge rates, multiple outputs switching, and operating at high frequencies, the output may have little or no level-shifting effect.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V,	I _I = –18 mA			–1.2	V
V _{OH}		See Figure 2					
I _I		V _{CC} = 5.5 V,	V _I = 5.5 V or GND			±1	μA
I _{CC}		V _{CC} = 5.5 V,	I _O = 0,			1.5	mA
		V _I = V _{CC} or GND					
ΔI _{CC} ⁽²⁾	Control input	V _{CC} = 5.5 V,	One input at 3.4 V,			2.5	mA
		Other inputs at V _{CC} or GND					
C _i	Control input	V _I = 3 V or 0				2	pF
C _{i(OFF)}		V _O = 3 V or 0,	\overline{OE} = V _{CC}			3.5	pF
r _{on} ⁽³⁾		V _{CC} = 4.5 V	V _I = 0	I _I = 64 mA	5	7	Ω
				I _I = 30 mA	5	7	
			V _I = 2.4 V,	I _I = 15 mA	35	50	

- (1) All typical values are at V_{CC} = 5 V, T_A = 25°C
- (2) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.
- (3) Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

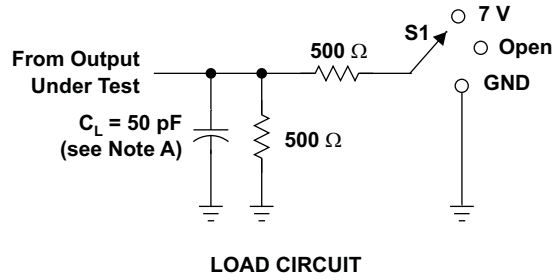
Switching Characteristics

over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see [Figure 1](#))

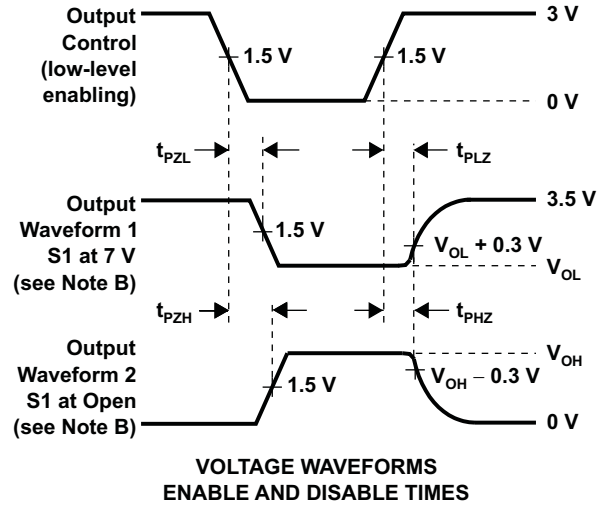
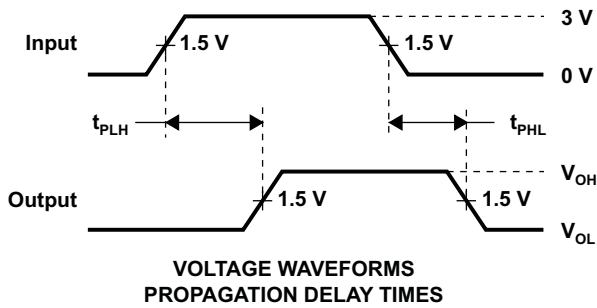
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN MAX		UNIT
$t_{pd}^{(1)}$	A or B	B or A		0.25	ns
t_{en}	\overline{OE}	A or B	2	5.9	ns
t_{dis}	\overline{OE}	A or B	1	4.7	ns

- (1) The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



TEST	S1
t_{pd}	Open
t_{pLZ}/t_{pZL}	7 V
t_{pHZ}/t_{pZH}	Open



NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.

Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ Mhz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.

D. The output is measured with one input transition per measurement.

E. t_{pLZ} and t_{pHZ} are the same as t_{dis} .

F. t_{pZL} and t_{pZH} are the same as t_{en} .

G. t_{pLH} and t_{pHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

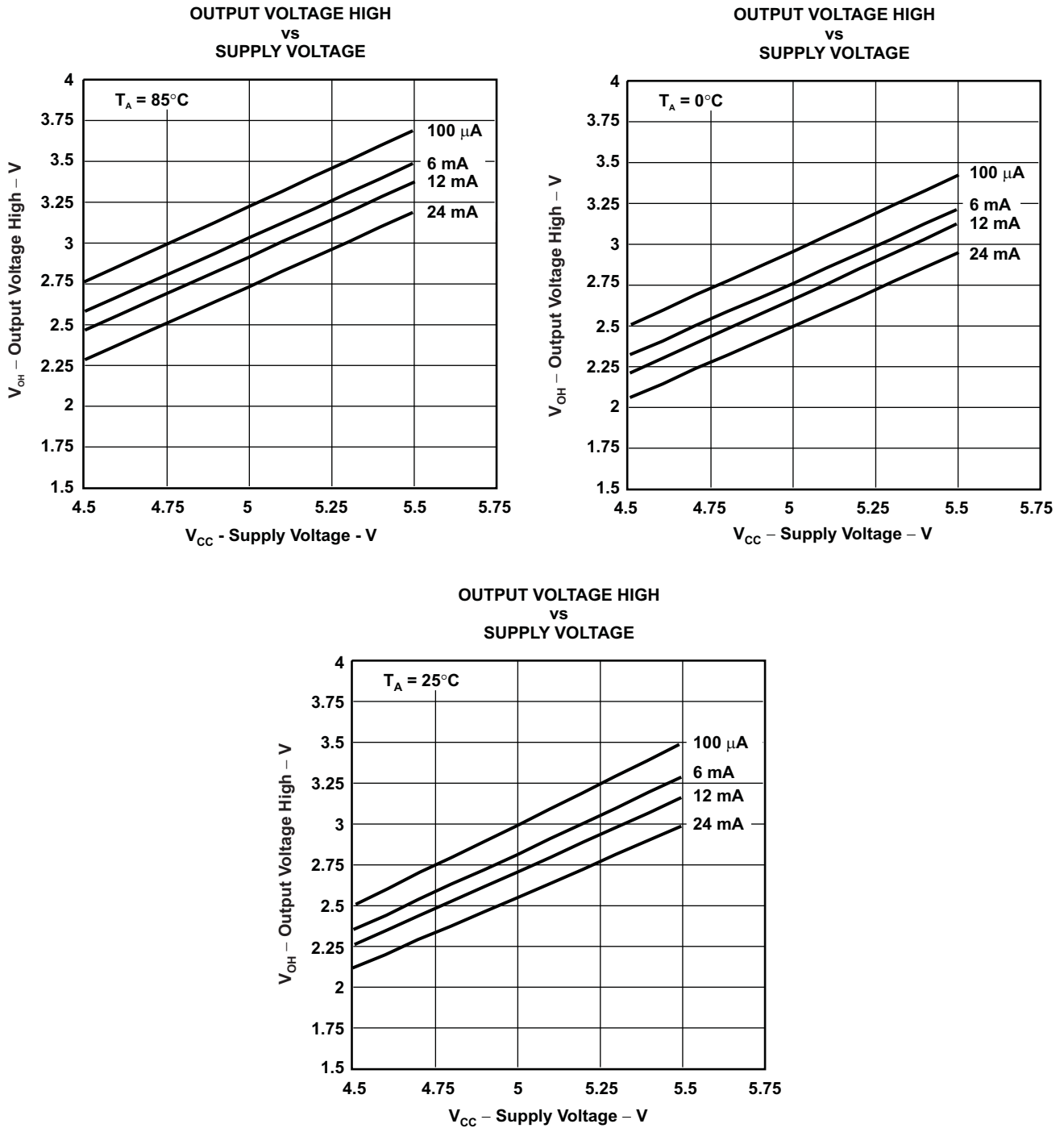


Figure 2. V_{OH} Values

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74CBTD1G384DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	(P8DG ~ P8DS)	Samples
SN74CBTD1G384DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	P8DS	Samples
SN74CBTD1G384DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	P8S	Samples
SN74CBTD1G384DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	P8S	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBTD1G384DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74CBTD1G384DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74CBTD1G384DBVT	SOT-23	DBV	5	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74CBTD1G384DCKR	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
SN74CBTD1G384DCKT	SC70	DCK	5	250	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBTD1G384DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
SN74CBTD1G384DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74CBTD1G384DBVT	SOT-23	DBV	5	250	202.0	201.0	28.0
SN74CBTD1G384DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
SN74CBTD1G384DCKT	SC70	DCK	5	250	202.0	201.0	28.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

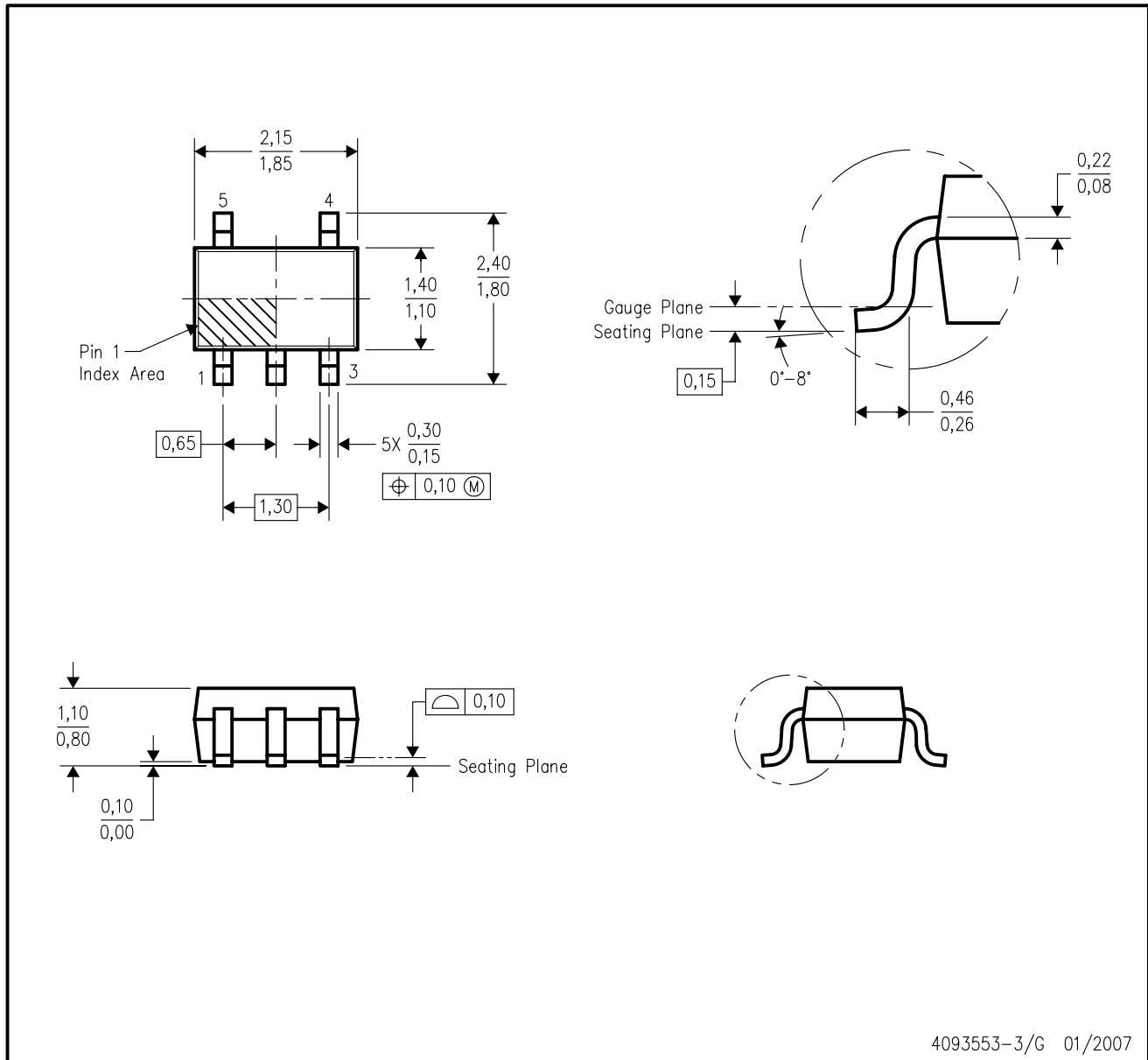
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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